Compliant with IEC 62474/ D9.00

MICROCHIP  Semiconductor Device Type: C5X 008 TSSOP 4.4mm Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	19.49	(mg) Total	Mold Compound	% ot Total Weight	59.06
Silica, vitreous	60676-86-0	Mold Compound	50,201	16.566	502,010		Silica, vitreous	60676-86-0	85.00	Ī
Epoxy Resin	Trade Secret	Mold Compound	3.617	1.194	36,174		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.617	1.194	36,174		Phenolic Resin	Trade Secret	6.13	1
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.447	0.478	14,470		Epoxy, Cresol Novolac		2.45	1
Carbon Black	1333-86-4	Mold Compound	0.177	0.058	1.772		Carbon Black	1333-86-4	0.30	1
Copper	7440-50-8	Lead Frame	30.020	9.907	300,200		Carbon Black	Total		<b>3</b>
Nickel	7440-02-0	Lead Frame	0.801	0.264	8.006	10.40	(mg) Total	Lead Frame	% of Total Weight	31.52
Silver	7440-22-4	Lead Frame	0.526	0.174	5,261	10.40	Copper	7440-50-8	95.24	31.32
Silicon	7440-21-3	Lead Frame	0.142	0.047	1,418		Nickel	7440-02-0	2.54	
	7440-21-3	Lead Frame		0.047						
Magnesium			0.032		315		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	1.008	0.333	10,080		Silicon	7440-21-3	0.45	
2,6-Diglycidyl phenyl allyl ether	EINECS (417-470-1)	Die Attach	0.056	0.018	560		Magnesium	7439-95-4	0.10	
Epoxy Resin	9003-36-5	Die Attach	0.056	0.018	560			Total		
Silicon	7440-21-3	Chip (Die)	6.300	2.079	63,000	0.37	(mg) Total	Die Attach	% of Total Weight	1.12
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.177	0.058	1,769		Silver	7440-22-4	90.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.003	0.001	32	2,6	-Diglycidyl phenyl allyl ethe	er EINECS (417-470-1)	5.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.820	0.601	18,200		Epoxy Resin	9003-36-5	5.00	
		TOTALS:	100.000	33.000	1.000.000			Total	100.00	
								Iotai	100.00	
	ith EU Directives	g Total Mass : 2002/95/EC (27 January 2003) & Directive 2011/65/EU (0			,,	2.08	Total (mg)  Doped Silicon	Chip (Die) 7440-21-3	% of Total Weight	6.30
5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption	ith EU Directives (zero)	: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (0			,,	2.08		Chip (Die)	% of Total Weight	6.30
) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via intern hemical substance is absent from the list above, the chemical su porated's knowledge and belief as of the date of this document,	ith EU Directives (zero) nal design contro ubstance is NOT , there is no cred	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0 ls, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ble reason to believe that the unavoidable impurity conce	8 June 2011) an	d 2015/863/EU Microchip Tec	J (31 March	2.08		Chip (Die) 7440-21-3	% of Total Weight	6.30
) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified via interr themical substance is absent from the list above, the chemical sur- prorated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulate ling compounds used by Microchip meet the UL94 V0 flammabili	ith EU Directives (zero) nal design contro ubstance is NOT , there is no cred ory scheme worl ity standard for p	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0 ls, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and lible reason to believe that the unavoidable impurity conce d-wide.	8 June 2011) and, to the best of ntration of the c	d 2015/863/EU Microchip Tec chemical subs	J (31 March		Doped Silicon	Chip (Die) 7440-21-3 Total Wire Bond Copper palladium	% of Total Weight 100.00 100.00	6.30
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5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption npliance with the above EU Directives has been verified via interrichemical substance is absent from the list above, the chemical supported is not below the threshold of regulatory concern for any regulating compounds used by Microchip meet the UL94 V0 flammabili c/lul.com/global/eng/pages/offerings/industries/chemicals/plastic protective "tubes" in which the specific product is shipped are nain "reels" may be made from PVC plastic.  Tochip Technology Incorporated believes the information in this for original packing materials is true and correct to the best of its k pleteness and accuracy of data in this form because it has been material in the second of the average weight of these parts and sided only as estimates of the average weight of these parts and	ith EU Directives (zero)  nal design contro  ubstance is NOT  there is no cred  ory scheme worl  ity standard for p  s/  nade from polyvi  form concerning  nowledge and be  compilled based  some information  the average weig  tero)	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0  Is, supplier declarations, and /or analytical test data.  an intentional ingredient in the semiconductor device and bible reason to believe that the unavoidable impurity conce d-wide.  clastics. You can access the UL iQTM family of databases  myl chloride (PVC) plastic. "Window envelopes" used to h  substances restricted by RoHS in Microchip Technology I  elief, as of the date listed in this form. Microchip Technolo on the ranges provided in Material Safety Data Sheets pro inay not have been provided by subcontract assemblers th of anticipated significant toxic metals components. The	a, to the best of intration of the coordinates to be obtain a test bold the packing incorporated's s gy Incorporated vided by raw m and raw materia	d 2015/863/EU Microchip Tec chemical subs report at slip on the ou emiconductor cannot guara aterial supplie	I (31 March chnology tance, if atter box and r devices in intee the rrs. Supplier iformation is		Doped Silicon  (mg) Total  Copper	Chip (Die) 7440-21-3 Total Wire Bond Copper palladium coated (CuPd) 7440-50-8	% of Total Weight 100.00 100.00 % of Total Weight 98.25 1.75	6.30
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s semiconductor device and its homogenous materials comply w (5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption impliance with the above EU Directives has been verified via interrochemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical suborporated's knowledge and belief as of the date of this document, is not below the threshold of regulatory concern for any regulate Iding compounds used by Microchip meet the UL94 V0 flammabilip://ul.com/global/eng/pages/offerings/industries/chemicals/plastice protective "tubes" in which the specific product is shipped are natin "reels" may be made from PVC plastic.  Prochip Technology Incorporated believes the information in this fir original packing materials is true and correct to the best of its knipleteness and accuracy of data in this form because it has been ormation is often protected from disclosure as trade secrets and swided only as estimates of the average weight of these parts and oppants, metals, and non-metal materials contained within silicon crochip Technology Incorporated does not provide any warranty, or tranties provided by Microchip Technology Incorporated and its solutions, sales order acknowledgement, and invoices.  Prochip disclaims any duty to notify users of updates or changes the cervise, suffered by users or third parties as a result of the users' this Certificate of Compliance for semiconductor products.	ith EU Directives (zero) (zero) ubstance is NOT t, there is no cred ory scheme worl ity standard for p solution of the complete form concerning mowledge and be compiled based some informatior the average weig devices (silicon express or implie ubsidiaries are c to Material Conte	2002/95/EC (27 January 2003) & Directive 2011/65/EU (0 lls, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ible reason to believe that the unavoidable impurity conced-wide.  clastics. You can access the UL iQTM family of databases in lateral semiconductor device and the lateral semiconductor of the lateral semiconductor of the lateral semiconductor of the lateral semiconductor on the ranges provided in Material Safety Data Sheets prounds in the finished semiconductor of the lateral semiconductor of	a, to the best of ntration of the or to obtain a test old the packing encorporated's say Incorporated yield by raw mand raw materiese estimates dition. The exclusiale. These are rect or indirect,	Microchip Techemical substreport at slip on the outer cannot guaraterial supplie on tinclude to consequential cons	thnology trance, if atter box and are devices in untee the rs. Supplier information is trace levels are deviced in the control of the control	0.06	Doped Silicon  (mg) Total  Copper  Palladium	Chip (Die)  7440-21-3  Total  Wire Bond Copper palladium coated (CuPd)  7440-50-8  7440-05-3  Total  Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1	% of Total Weight 100.00 % of Total Weight 98.25 1.75 100.00 % of Total Weight 100.00	0.18

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